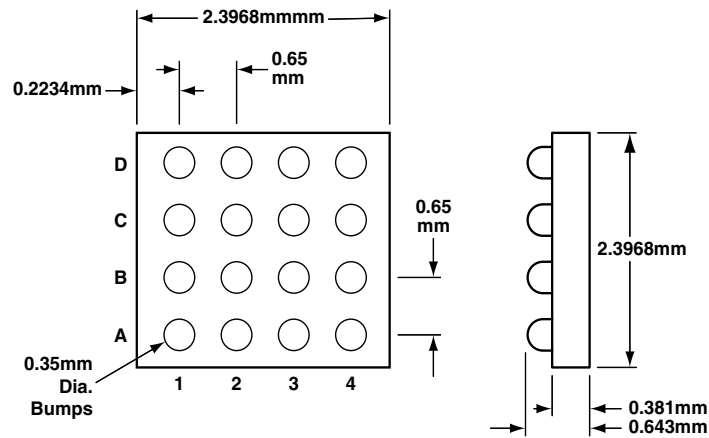


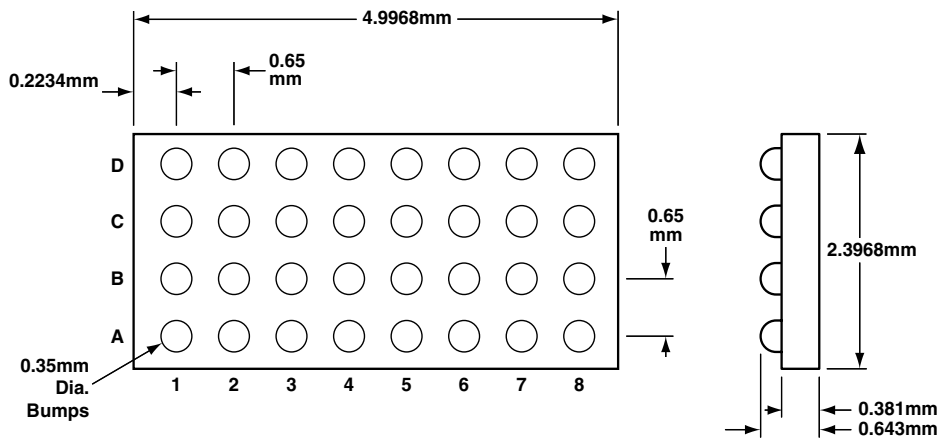




Package Diagram (Bumps Up View)



CSPST08

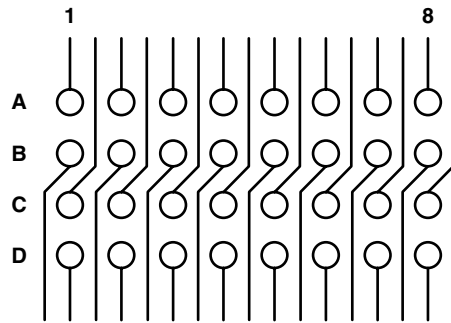


CSPST16

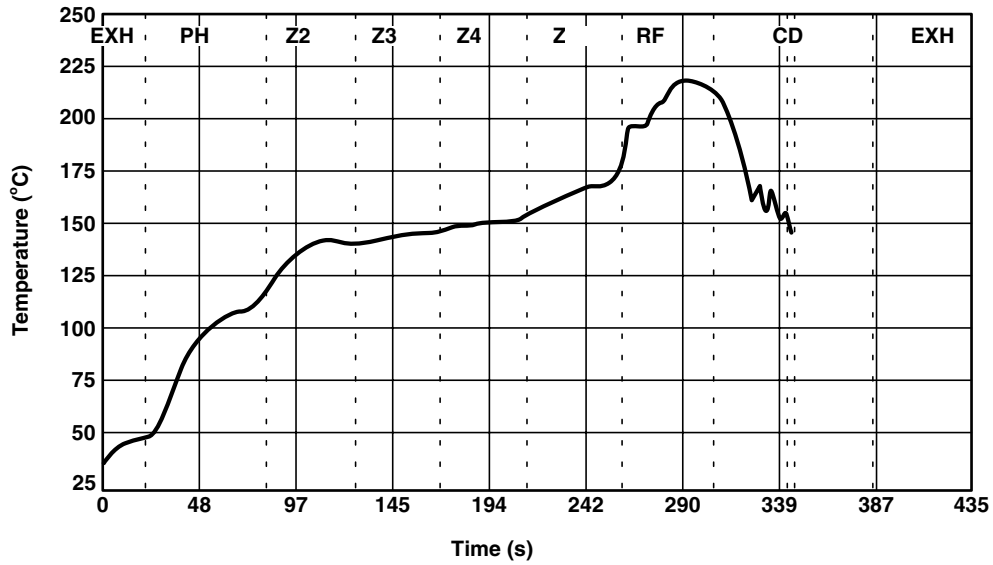
PRINTED CIRCUIT BOARD RECOMMENDATIONS	
Pad Size on PCB	0.300mm
Pad Shape	Round
Pad Definition	Non Solder Mask Defined Pads (NSMD)
Solder Mask Opening	0.350mm
Solder Stencil Thickness	0.152mm
Solder Stencil Aperture Opening	0.360mm (sq.)
Solder Flux Ratio	50/50
Solder Paste	No Clean
Bond Trace Finish	OSP (Entek Cu Plus 106A)



Typical PCB Routing Diagram (Bumps Down View)



Typical Solder Reflow Thermal Profile (No Clean Flux)





STANDARD PART ORDERING INFORMATION			
Package		Ordering Part Number	
Style	Terminations	Tape & Reel	Part Marking
Chip Scale	8	CSPST08-220F	None
Chip Scale	8	CSPST08-220J	None
Chip Scale	8	CSPST08-330F	None
Chip Scale	8	CSPST08-330J	None
Chip Scale	8	CSPST08-390F	None
Chip Scale	8	CSPST08-390J	None
Chip Scale	8	CSPST08-470F	None
Chip Scale	8	CSPST08-470J	None
Chip Scale	8	CSPST08-510F	None
Chip Scale	8	CSPST08-510J	None
Chip Scale	8	CSPST08-560F	None
Chip Scale	8	CSPST08-560J	None
Chip Scale	16	CSPST16-220F	None
Chip Scale	16	CSPST16-220J	None
Chip Scale	16	CSPST16-330F	None
Chip Scale	16	CSPST16-330J	None
Chip Scale	16	CSPST16-390F	None
Chip Scale	16	CSPST16-390J	None
Chip Scale	16	CSPST16-470F	None
Chip Scale	16	CSPST16-470J	None
Chip Scale	16	CSPST16-510F	None
Chip Scale	16	CSPST16-510J	None
Chip Scale	16	CSPST16-560F	None
Chip Scale	16	CSPST16-560J	None

PACKAGE		NON-STANDARD PART ORDERING INFORMATION	
Part Series	Terminations	Value Code: R1 (XXX)	Tolerance
<i>Example (CSPST)</i>	<i>(8)</i>	<i>(201)</i>	<i>(J)</i>
CSPST	8	First 2 digits are significant value. Third digit represents number of zeros to follow	F = ±1%
CSPST	16		J = ±5%

